

AMENDMENTS TO THE SPECIFICATION

Please amend the title as follows:

TUBE CONNECTING APPARATUS~~JOINING DEVICE~~

Please replace paragraph [0067] of the application as filed with the following amended paragraph:

[0067] Next in step 620, the CPU 191 drives the cam motor 150, then in step 622, judges as to whether or not the transmission type sensor 196 detects the notch 198. When a negative judgment is made, the CPU 191 continues to drive the cam motor 150, while when an affirmative judgment is made, the CPU 191 stops driving of the cam motor 150 in step 624. Then in step 626, the CPU 191 makes the EEPROM 500 to renew the information with respect to a connecting process state from the information expressing being in a state of tube ~~[[non-]]~~connecting operation to information expressing being in a state of tube non-connecting operation (e.g., "0")), subsequently in step 628, makes the wafer current controlling section to stop electricity supply to the wafer 41 in order to stop heating of the wafer 41.

Please replace paragraph [0077] of the application as filed with the following amended paragraph:

[0077] The CPU 191 judges as to whether or not the wafer feeding member 115 moves more than a predetermined amount (30mm in this embodiment, See the wafer feeding member ~~45-~~115 shown by a two dotted line in FIG. 25.) from the wafer

feeding start position to a direction of the wafer feeding end position. When a negative judgment is made, the CPU 191 continues to grasp the position of the wafer feeding member 115. Incidentally, in this embodiment, the moving amount of the wafer feeding member 115 for feeding the wafer 41 is set to approximately 55 mm.

Please replace paragraph [0081] of the application as filed with the following amended paragraph:

[0081] In the next step 720, the CPU 191 makes the EEPROM 500 to renew the exchange information of the wafer 41 from the information expressing being ~~exchanged~~ unexchanged (e.g., "0") to the information expressing being ~~unexchanged~~ (e.g., "0") exchanged, then the wafer exchanging subroutine is finished to proceed to step 800 in FIG. 14.

Please replace paragraph [0094] of the application as filed with the following amended paragraph:

[0094] In the next step 826, because the connecting operation of the tubes 8, 9 is finished, the CPU 191 renews the information with respect to the connecting process state in the EEPROM 500 from the information expressing being in a state of connecting operation to the latest information expressing being in a state of non-connecting operation. In the next step 828, the CPU 191 makes the wafer current controlling section to stop supplying electricity to the wafer 41 in order to stop heating of the wafer 41, then in the next step 830, waits until the cooling time of the

wafer 41 lapses. When the cooling time lapses, the CPU 191 makes the clamp lock solenoid controlling section 506 to demagnetize the clamp lock solenoid 400 to cancel the locking state in step 832. Then, in step 834, the CPU 191 reads out the accumulated connecting number memorized in the EEPROM 500 to increase the number by 1, and makes the EEPROM 500 to memorize (renew) the increased accumulated connecting number as the latest accumulated connecting number, thereby the tube connecting subroutine is finished and the routine proceeds to step 700 in FIG. [[4]]14. Thus, execution of one tube connecting routine is completed.

Please replace paragraph [0117] of the application as filed with the following amended paragraph:

[0117] (Description of the Numerals)

1 tube connecting apparatus

6 first clamp (holding section)

7 second clamp (holding section)

8, 9 tube

41 wafer (cutting plate)

100 wafer feeding mechanism (cutting plate conveying section)

132, 133 transmission type sensor (cutting plate conveying section detecting sensor)

140 wafer holder (cutting section)

145 electrode portion

150 cam motor (a part of a holding section movement unit, a part of a cutting section movement unit)

156 driving shaft (a part of a holding section movement unit, a part of a cutting section movement unit)

159 cam (a part of a cutting plate movement unit)

190 controlling section (a part of a controlling section)

192 LCD display (display section)

195, 196 transmission type sensor (position detecting sensor)

200 drive-conveying mechanism (a part of a holding section movement unit means, a part of a cutting section movement unit means, a part of a cutting plate movement means conveying section)

400 clamp lock solenoid (engagement section)

410 clamp lock detecting sensor (holding section lock sensor)

421 wafer position detecting sensor (cutting section detecting sensor)